External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00156	100.0	0.03313
			Subtotal	0.00156	100	0.03313
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.04225	90.0	0.9
	Tin alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00023	0.5	0.005
	Tin alloy	Silver (Ag)	7440-22-4	0.00117	2.5	0.025
	Tin alloy	Antimony (Sb)	7440-36-0	0.00329	7.0	0.07
			Subtotal	0.04694	100	1
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01219	100.0	0.25977
			Subtotal	0.01219	100	0.25977
Die	Doped silicon	Silicon (Si)	7440-21-3	0.32391	100.0	6.9
			Subtotal	0.32391	100	6.9
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.0169	0.03	0.36
	Copper alloy	Iron (Fe)	7439-89-6	0.05633	0.1	1.2
	Copper alloy	Copper (Cu)	7440-50-8	56.25969	99.87	1,198.44
			Subtotal	56.33292	100	NaN
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.26749	100.0	27
			Subtotal	1.26749	100	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00563	0.03	0.12
	Copper alloy	Iron (Fe)	7439-89-6	0.01878	0.1	0.4
	Copper alloy	Copper (Cu)	7440-50-8	18.75323	99.87	399.48
			Subtotal	18.77764	100	400
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.05868	5.0	1.25
	Lead alloy	Silver (Ag)	7440-22-4	0.02934	2.5	0.625
	Lead alloy	Lead (Pb)	7439-92-1	1.08558	92.5	23.125
			Subtotal	1.1736	100	25
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0.00422	0.1	0.09
	Copper alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.87007	91.6	82.44
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.03802	0.9	0.81
	Copper alloy	Molybdenum (Mo)	7439-98-7	0.29575	7.0	6.3
	Copper alloy	Manganese (Mn)	7439-96-5	0.0169	0.4	0.36
			Subtotal	4.22496	100	90
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.26758	1.5	5.7
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	1.69468	9.5	36.1
	Filler	Silica fused	60676-86-0	15.69811	88.0	334.4
	Carbon Black	Carbon black	1333-86-4	0.17839	1.0	3.8
			Subtotal	17.83876	100	380
			Total	99.99997	100	NaN

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